

STRETCH.FLEX 2.0 – WE STRETCH THE LIMITS OF DESIGN!

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WURTH ELEKTRONIK MORE THAN YOU EXPECT

AGENDA

STRETCH.flex 2.0 – we stretch the limits of design!

- 1. Review
- 2. Results of Stretchability
- 3. Layouting in EDA-Tool
- **4**. Assembly of components
- 5. Applications



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Review

- Thermoplastic polyurethane (TPU) acts as new copper clad substrate material
- Design of the tracks in meander form to realize the stretchability
- Various further processing options e.g. thermoforming/deep drawing, back injection moulding, laminating, etc.:
- Wide property profile of TPU e.g. skin-friendly, free from softeners, UV and radiation resistant



Laminated onto textiles Source: Fraunhofer IZM



Example "Conformable Electronics" Source: Fraunhofer IZM



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BASICS

Possibilities for the design

 Stretchability of the tracks is realized with tracks in meander form

- Track width and spacing
 100 µm
 200 µm
 300 µm
- Final copper thickness
 - 18 µm
 - 35 µm

 Transition between rigid and stretchable area



Donut-Structure







Meanderstyle*	Cycles 5%	Cycles 10%	Cycles 20%
Horseshoe big	2650	509	92
Horseshoe small	4499	742	129
Rectangle	8585	1122	139
Wave	2288	406	61

The greater the elongation, the fewer cycles can be achieved. Best result: Rectangular structure



*Source: Order investigation Fraunhofer IZM











- Radii of the rectangles are adjusted by FEM simulation
- Goal: Show optimization potential

At 100 μm radius, stress values decrease by approx. 10%.





ELONGATION - FINE ANALYSIS

- Improved structure of expansion system and receptacles
- Physically tested approx. 1200 meander structures
- Differentiation in terms of
 - Track Width
 - Opening angle
 - Ratio
 - Meander Structure



ELONGATION - FINE ANALYSIS

- The resistance is measured at the min. and max. elongation points
- Promising layouts are simulated with FEM simulation
- Tests still on going



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DESIGN TOOL POSSIBILITIES

Meander structures generated in the tool

live - Demo



OPPORTUNITIES FOR DESIGN-TOOL

Meander structures generated in the tool

different meander styles:
 Full Arc, Snake, Triangular and Square

arbitrarily routed and rounded traces



• various meanders superposed to sinusoidally designed basic structure



traces overlaid with full arc meanders









OPPORTUNITIES FOR DESIGN-TOOL

Opportunities for Design-Tool

prepared stretch design with rounded traces

 complete design is provided with previously selected meander structures at the push of a button





STRETCH.FLEX

Opportunities for Design-Tool





OPPORTUNITIES FOR DESIGN-TOOL

Allegro

- Control panel with selection option of the different patterns and their parameters such as linewidth, space, radius, offset, etc.
- the transition areas between In stretchable and reinforced circuit carrier there are donut structures to create a defined transition.
- These transition areas are predefined by regions/shapes.



Source: FlowCAD



OPPORTUNITIES FOR DESIGN-TOOL

Overview of different meander structures

Options e ×	Options e ×	Options _ & ×	Options & ×	Options & ×
FlowCAD Licensed for: Wuerth, Nierdernhall General Active subclass Connect pad None	FlowCAD Licensed for: Wuerth,Nierdernhall General Active subclass	FlowCAD Licensed for: Wuerth,Nierdernhall General Active subclass Connect pad	FlowCAD Licensed for: Wuerth, Nierdernhall General Active subclass	FlowCAD Licensed for: Wuerth, Nierdernhall General Active subclass
Start offset 1.00 End offset 1.00 Vertex round Save previous pattern on commit Smooth path Max length 0.40 Radius 0.50	Start offset 1.00 End offset 1.00 Vertex round	Start offset 1.00 End offset 1.00 Vertex round	Start offset 1.00 End offset 1.00 Vertex round	Connect padNoneStart offset1.00End offset1.00Vertex round
Type Full Arc F	Type Snake Snake COORDENSE Line width (W): 0.20 Gap (G): 0.80 Angle span (A): 270.00	Type Triangular Line width (W): 0.20 Gap (G): 0.80 Height (H): 0.80 Vertex radius (R): 0.20	Pattern parameters Type Square Line width (W): 0.20 Gap (G): 0.80 Height (H): 0.80	Pattern parameters Type Double snake Line width (W): 0.20 Gap (G): 0.80

Source: FlowCAD



STRETCH.FLEX

Short survey: with multiple answer options

- We would like to further develop the technology with our partners. Which tool would you prefer for the next implementation:
 - Altium
 - Cadence (Allegro / OrCAD)
 - Siemens (Pads / Expedition)
 - Zuken
 - others





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Solder carrier, soldering process (low-melting alloy)

• for transport through the soldering oven, the polyurethane circuit carrier must be reinforced by a support material





PASTE APPLICATION - STENCIL



- possible challenges may be the above-average height differences when using use of additive solder resist can be
- in combination with miniaturized components, e.g. ≤ IPC 0201, the bulges on the top side of the PCB, or bottom side of the paste stencil must be compensated.
 - this can be achieved by cavities on the bottom side of the paste stencil
 - ask the stencil manufacturer for minimum milling diameter!
 - thus an optimal sealing towards the PCB can be achieved.





Assembly process

Lowering the process temperature by adding bismuth to the alloy





Conserving resources

- Due to the significantly reduced process temperature, up to 40% of the electrical energy can be saved.
- Compared to a SAC 305 solder paste, the use of tin-bismuth alloys can reduce CO2 emissions per furnace by almost 57 tons.

Cost Saving: Reduced Electricity Consumption



40% Reduction in Electricity Consumption

Measured Parameter	SAC Reflow	BiSnAg Reflow
Current (RMS), amps	60.4	36.7
Power (Average), Kilowatts	29.3	17.8

LTS vs. SAC Reflow Electrical Usage

Estimated SMT Process Energy Cost Comparison								
SAC 305 Paste		Sn/Bi/Ag Paste						
29.5	Oven Energy Consumption (Kw)	17.						
134.4	80% Utillzation (Hours/Wk)	134.						
0.0007		0.000						
2.78		1.6						
CO2 Savings (metric tons per oven/week)								
CO2 Savings (metric tons per oven/yr)								
	29.5 29.5 134.4 0.0007 2.78 ven/we ven/yr)	rocess Energy Cost Comparison Sn/Bi/Ag Paste 29.5 Oven Energy Consumption (Kw) 134.4 80% Utillzation (Hours/Wk) 0.0007 2.78 ven/week) ven/yr)						





STRETCH.FLEX

Short survey: multiple choice with only one correct answer

Is this a technology that is of interest to you?

- Yes, I already have a project.
- Yes, but only in one two years.
- Yes, but not for another five years.
- No.





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Medical Technology

Sentec Co. – Neonatology Belt

- Treatment of new-borns and premature babies (neonatology)
- Chest strap to directly monitor the lung and heart function through electrical impedance tomography (EIT)
- Advantage against previous solution: Significantly reduced risk of injury to the sensitive skin









Smart Textiles / Wearable Technology

Fraunhofer IZM and Designer Wolfgang Langeder (Utope Co.) / Cycling Jacket "Sporty Supaheroe"

- Integrated and active sensor-controlled LEDs for an interactive safety lighting
- Red Dot Design Award "Design Concept"





Medical Technology

- Fa. Binder Elektronik sensor device close to the body
 - Monitoring of Dementia patients
 - Band for automatic recording of health and care data
 - Advantage against previous solution: functionalization of the complete band



Medical Technology

- Electrode arrays for EMD application
- Rehabilitation of stroke patients using electrical muscle stimulation
- Stimulation of muscle parts via single or multiple elements to regain autonomous movement ability







Medical Technology

- Multimodal monitoring concept with wearable patch
 - ECG, skin temperature, Impedance pneumography as well as photoplethysmography (PPG) measurments
 - High degree of miniaturization and dense integration results in a inconspicuous shape
 - The use of TPU has increased the wearing comfort







COOPERATION PARTNER







THANKS FOR YOUR ATTENTION!

What kind of application do you have? How can WE support you? Kontakt:

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